Title
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Sub-Ångstrom TEM to a resolution of 0.78Å has been demonstrated by the one-Ångstrom microscope (OÅM) project at the National Center for Electron Microscopy. The OÅM combines a modified CM300FEG-UT with computer software1,2 able to generate sub-Ångstrom images from experimental image series.

Sub-Ångstrom HREM is gaining in importance as researchers design and build artificially-structured nanomaterials such as semiconductor devices, ceramic coatings, and nanomachines. Commonly, such nanostructures include atoms with bond lengths shorter in projection than the point resolution of a mid-voltage HREM3. In addition, image simulations have shown that structure determinations of defects such as dislocation cores require sub-Ångstrom resolution4, as will hold true for grain boundaries and other interfaces.

Sub-Ångstrom microscopy with a transmission electron microscope requires meticulous attention to detail. As resolution is improved, resolution-limiting parameters need to be reduced. In particular, aberrations must be minimized, power supplies must be stabilized, and the microscope environment optimized to reduce acoustic and electromagnetic noise in addition to vibration. Figure 1 shows limits for several important parameters. To reach a direct resolution of \( d_s \), the spherical aberration coefficient \( C_s \) needs to be below \( 6d_s^4/\lambda^3 \). Thus, to reach 0.8Å at 300keV (fig.1), \( C_s \) should be less than 0.03mm (0.02mm would be optimum5).

Alternatively, to reach an information limit of \( d_\lambda \) by focal reconstruction requires the standard deviation of focus spread \( \Delta \) to be less than \( 2d_\lambda^2/(\pi\lambda) \), or 21Å at 300keV for \( d_\lambda=0.8\text{Å} \). Two- and three-fold astigmatism, \( A_2 \) and \( A_3 \) must be kept low. To ensure phase distortions of less than \( \pi/4 \) at resolutions of \( d_\lambda \) and \( d_\lambda^2 \), \( A_1 \) and \( A_2 \) must be below \( d_\lambda^2/(4\lambda) \) and \( 3d_\lambda^3/(8\lambda^2) \) respectively, or 8Å and 500Å to reach 0.8Å at 300keV. Even specimen thickness must be reduced6 to less than 2\( d_s^2/\lambda \), requiring less than 65Å to reach 0.8Å at 300keV.

Sub-Ångstrom resolution was achieved with the OÅM by placing the TEM in a favorable environment7, and by reducing its three-fold astigmatism \( A_2 \) and information limit \( d_\lambda \). Before correction, \( A_2 \) was measured as 2.46μm (fig.2a); after correction, as 300Å (fig.2b), corresponding to 0.68Å at a \( \pi/4 \) phase limit. Measurement of the energy spread (gun spread plus high-voltage ripple) as 0.93eV FWHH indicated a focus spread \( \Delta \) of 20Å and an information limit of 0.78Å (fig.1). Tests with a diamond specimen showed that \( A_2 \) was corrected and the OÅM could successfully resolve the 0.89Å (400) dumbbell spacings in [110] diamond3,8,9.

Sub-Ångstrom resolution is improved by lowering the TEM information limit. Measurements showed that the expected limit could be lowered below 0.75Å by reducing the gun extraction voltage (fig.3). As a test, we have imaged the 0.78Å (444) dumbbell spacings in [112] silicon. The 444 reflections have optimum transfer \( \Delta \) of 0.8Å. Two- and three-fold astigmatism, \( A_1 \) and \( A_2 \) must be below \( d_\lambda^2/(4\lambda) \) and \( 3d_\lambda^3/(8\lambda^2) \) respectively, or 8Å and 500Å to reach 0.8Å at 300keV. Even specimen thickness must be reduced6 to less than 2\( d_s^2/\lambda \), requiring less than 65Å to reach 0.8Å at 300keV.

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Fig. 1 Resolution-limiting parameters plotted for spatial frequency (top) from 0.5 to 2.0 Å⁻¹ and resolution from 2.0 to 0.5 Å (bottom) for 300 keV. Spherical aberration $C_S$ (mm), 3-fold astigmatism $A_3$ (µm) and vibration $v(\text{Å})$ are plotted from 0 to 1 (left). Spread of focus $\Delta$, 2-fold astigmatism $A_2$, and specimen thickness $H$ range from 0 to 100 Å (right).

Fig. 2. Measured 3-fold astigmatism before (a) and after (b) correction. Mean values are hollow. Mean in (a) is 2.46 µm. Means in (b) are 0.03 µm, corresponding to $\pi/4$ at 0.68 Å.

Fig. 3. As extraction voltage is reduced from 4.0 keV, measured FWHH energy spread $\delta E_T$ (eV) falls from 0.93 eV, and information limit $d_A$ falls from 0.8 Å.

Fig. 4. Plot of beam phases shows position of $\alpha$-null defocus for 0.78 Å.

Fig. 5. Diffractogram from Si[112] image has intensities that exhibit linear-transfer Fourier-defocus behavior down to 0.78 Å.

Fig. 6. Images of Si[112] show separation of 0.78 Å Si-Si dumbbells. (a) “white-atom” image. (b) “black-atom” dumbbell is difficult to see, but profile (averaged vertically over 6 dumbbells) shows separation.